

**Amendment to the Abstract:**

Kindly insert the Abstract, which is attached as a separate sheet to this Amendment,  
as a separate page of the present application.

**ABSTRACT**

A method of forming a semiconductor device from a semiconductor substrate (1) comprising circuitry (2) and terminal means (3) for establishing  
- 5 electrical connection to the circuitry; and a sheet (4) for forming a further  
layer of the device, the sheet comprising at least one groove (5). Adhesive is  
applied to at least one of the substrate (1) and the sheet (4); the substrate and  
the sheet are then aligned in a position such that the groove (5) faces the  
terminal means (3); and the substrate and the sheet are then attached  
10 together by means of the adhesive.